L Number	Hits	Search Text	DB	Time stamp
1	477		USPAT;	2003/12/15 08:35
		pad) (mounting adj (pad portion region	US-PGPUB;	
		area))) and (loc (lead adj1 chip))	EPO; JPO;	
_	212	(/leadframe /lead add frame)) and (/die add	DERWENT	2003/12/15 08:36
2	312	((leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region	USPAT; US-PGPUB;	2003/12/15 08:36
		area))) and (loc (lead adj1 chip))) and	EPO; JPO;	
į		((sealing adj resin) encapsula\$4)	DERWENT	
3	88	(((leadframe (lead adj frame)) and ((die	USPAT:	2003/12/15 08:38
		adj pad) (mounting adj (pad portion region	US-PGPUB;	
		area))) and (loc (lead adj1 chip))) and	EPO; JPO;	
		((sealing adj resin) encapsula\$4)) and	DERWENT	
		((tie connect\$3) adj bar)		
-	0		USPAT;	2001/10/22 13:21
ì		adj pad) (mounting adj (pad portion region	US-PGPUB;	
		area))) and (loc (lead adj1 chip))").PN.	EPO; JPO; DERWENT	
_	303	(leadframe (lead adj frame)) and ((die adj	USPAT;	2003/12/15 08:35
_	303	pad) (mounting adj (pad portion region	US-PGPUB;	2003/12/13 00:33
		area))) and (loc (lead adj1 chip))	EPO; JPO;	
ļ		, , , , , , , , , , , , , , , , , , ,	DERWENT	
-	117	((leadframe (lead adj frame)) and ((die adj	USPAT;	2003/12/15 08:36
		pad) (mounting adj (pad portion region	US-PGPUB;	
1	!	area))) and (loc (lead adj1 chip))) not	EPO; JPO;	
		(((leadframe (lead adj frame)) and ((die	DERWENT	· ·
		adj pad) (mounting adj (pad portion region		1
		area))) and (loc (lead adj1 chip))) and ((sealing adj resin) encapsula\$4))		1
_	31		USPAT;	2002/04/29 12:57
_	51	near lead) and (loc (lead adj1 chip))	US-PGPUB;	2002/04/23 12:37
		nour road, and (roo (road days onep))	EPO; JPO;	
			DERWENT	·
-	10146	(loc (lead adj1 chip))	USPAT;	2002/06/15 10:47
			US-PGPUB;	1
			EPO; JPO;	:
	740		DERWENT	2002/12/15 22 27
_	740		USPAT;	2003/12/15 08:37
		encapsualted encapsualate (sealing adj resin) (molding adj compound))	US-PGPUB; EPO; JPO;	
		lesin, (moraring adj compound)	DERWENT	
-	322	(((loc (lead adj1 chip))) and	USPAT;	2002/06/15 10:51
		(encapsulating encapsualted encapsualate	US-PGPUB;	
		(sealing adj resin) (molding adj	EPO; JPO;	
		compound))) and (bending bent bend)	DERWENT	
-	317		USPAT;	2001/11/12 09:07
		(encapsulating encapsualted encapsualate	US-PGPUB;	
		(sealing adj resin) (molding adj compound))) and (bending bent bend)) and	EPO; JPO; DERWENT	
		(adhesive glue bonding bonded bond)	DEKARMI	
_	153	((loc (lead adj1 chip))) and disturbing	USPAT;	2001/11/12 09:32
į			US-PGPUB;	
			EPO; JPO;	
			DERWENT	
-	0	((loc (lead adj1 chip))) and (disturbing	USPAT;	2001/11/12 09:32
		near plate)	US-PGPUB;	
		•	EPO; JPO;	
_	5	(((loc (lead adj1 chip))) and	DERWENT USPAT;	2001/11/12 09:32
_	3	(((100 (1ead ad)1 chip))) and (encapsulating encapsualted encapsualate	US-PGPUB;	2001/11/12 09.32
		(sealing adj resin) (molding adj	EPO; JPO;	
		compound))) and disturbing	DERWENT	
	1	5932923.URPN.	USPAT;	2001/11/13 06:48
	-		US-PGPUB;	
			EPO; JPO;	
			DERWENT	
-	0	6153923.URPN.	USPAT;	2001/11/13 06:58
ļ			US-PGPUB;	
			EPO; JPO;	
ļ			DERWENT	

				T 0001 (11 1 1 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2
-	0	6153923.URPN.	USPAT;	2001/11/13 06:58
			US-PGPUB;	ļ
			EPO; JPO; DERWENT	
	1	E022022 HDDM	USPAT:	2001/11/13 06:58
_	1	5932923.URPN.	US-PGPUB;	2001/11/13 00.38
			EPO; JPO;	1
			DERWENT	
_	3	.5897339.URPN.	USPAT:	2001/11/13 07:33
	Ů		US-PGPUB;	
			EPO; JPO;	
			DERWENT	
_	1	5530286.pn. and epoxy	USPAT;	2001/11/13 09:08
!			US-PGPUB;	
			EPO; JPO; DERWENT	
	1	5932923.URPN.	USPAT;	2001/11/13 07:53
_	1	3932923.0KFN.	US-PGPUB;	2001,11,13 0,133
			EPO; JPO;	
			DERWENT	1
_	26	5535509.URPN.	USPAT;	2001/11/13 07:59
	Į į		US-PGPUB;	
			EPO; JPO;	
		6004.070 PP.DV	DERWENT	2001/11/13 08:02
j –	0	6291273.URPN.	USPAT; US-PGPUB;	2001/11/13 08:02
			EPO; JPO;	
			DERWENT	
_	0	6291273.URPN.	USPAT;	2001/11/13 08:02
l			US-PGPUB;	
			EPO; JPO;	
}		1	DERWENT	2001/11/12 00:40
-	1	5530286.pn. and polyimide	USPAT; US-PGPUB;	2001/11/13 09:40
			EPO; JPO;	
{			DERWENT	
_	636	257/667	USPAT;	2001/11/13 09:40
			US-PGPUB;	1
			EPO; JPO;	
			DERWENT	0001 (11 (10 10 10
-	96	257/667 and (encapsulating encapsualted	USPAT;	2001/11/13 12:19
		encapsualate (sealing adj resin) (molding	US-PGPUB; EPO; JPO;	
		adj compound)) and (bending bent bend)	DERWENT	
_	11	"09/449,834" and "Nikkei Microdevice"	USPAT;	2001/11/13 12:21
	1		US-PGPUB;	
			EPO; JPO;	
ì]		DERWENT	0000 (04 (00 10 ==
-	222	((leadframe (lead adj frame)) and ((die adj	USPAT;	2002/04/29 12:56
		pad) (mounting adj (pad portion region	US-PGPUB;	}
1	(area))) and (loc (lead adj1 chip))) and ((sealing adj resin) encapsula\$4)	EPO; JPO; DERWENT	
_	6	(((leadframe (lead adj frame)) and ((die	USPAT;	2002/04/29 12:59
1] "	adj pad) (mounting adj (pad portion region	US-PGPUB;	
]]	area))) and (loc (lead adj1 chip))) and	EPO; JPO;	
1	-	((sealing adj resin) encapsula\$4)) and	DERWENT	
		(dummy near lead)		0000 (0.455)
-	75	1 ' ' ' = ' ' ' ' ' ' ' ' ' ' ' ' ' ' '	USPAT;	2002/04/29 13:00
	ļ	adj pad) (mounting adj (pad portion region	US-PGPUB;	
		area))) and (loc (lead adj1 chip))) and	EPO; JPO; DERWENT	
		((sealing adj resin) encapsula\$4)) and ((bent bend bending) near3 lead)	DEKMENI	
L	<u> </u>	((bent bend bending) hears lead)		L

_	73	adj pad) (mounting adj (pad portion region area))) and (loc (lead adj1 chip))) and ((sealing adj resin) encapsula\$4)) and ((bent bend bending) near3 lead)) not ((((leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/29 13:00
		area))) and (loc (lead adj1 chip))) and ((sealing adj resin) encapsula\$4)) and		
		(dummy near lead))		
_	8	<pre>(((leadframe (lead adj frame)) and ((die adj pad) (mounting adj (pad portion region area))) and (loc (lead adjl chip))) and ((sealing adj resin) encapsula\$4)) and ((bent bend bending) near3 (inner near lead))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/29 13:01
-	8	1	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/04/29 13:01
-	10727		USPAT;	2002/05/10 08:22
			US-PGPUB; EPO; JPO; DERWENT	
_	149	((loc (lead adj1 chip))) and (flat near1 package)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/10 08:23
-	83	(((loc (lead adj1 chip))) and (flat near1 package)) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/10 08:25
_	71	((((loc (lead adj1 chip))) and (flat near1 package)) and solder) and (substrate pcb (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/10 08:26
-	54	<pre>(((((loc (lead adjl chip))) and (flat nearl package)) and solder) and (substrate pcb (printed adj circuit adj board))) and (resin encapsulant sealing)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/10 08:26
_	84	(((loc (lead adj1 chip))) and (flat near1 package)) and (solder (bonding adj material))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/10 08:25
_	72	((((loc (lead adj1 chip))) and (flat near1 package)) and (solder (bonding adj material))) and (substrate pcb (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/10 08:26
-	55	<pre>(((((loc (lead adj1 chip))) and (flat near1 package)) and (solder (bonding adj material))) and (substrate pcb (printed adj circuit adj board))) and (resin encapsulant sealing)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/10 08:29
-	4	5998866.URPN.	USPAT	2002/06/03 07:25
_	1 24	6258624.URPN. ("Re36613" "5214307" "5220195"	USPAT USPAT	2002/06/03 07:26 2002/06/03 07:26
	24	"5291059" "5365107" "5437915" "5442231" "5498901" "5594234" "5637915" "5638596" "5767560" "5767572" "5770479" "5814877" "5905299" "5920114" "5998866" "6002165" "6043430" "6049125" "6068180" "6075283" "6078099").PN.	OSTAT	2002/00/03 07.20
_	2	6078099.URPN.	USPAT	2002/06/03 07:27
L -	2	("5172214" "5291059").PN.	USPAT	2002/06/03 07:27

			I TIONAGE	10000/06/02 02 02
_	4	6068180.URPN.	USPAT	2002/06/03 07:29
-	21	("Re36613" "5214307" "5220195"	USPAT	2002/06/03 07:30
1		"5291059" "5365107" "5437915"		
		"5442231" "5498901" "5594234" "5637915" "5638596" "5767570"		
İ		, , , , , , , , , , , , , , , , , , , ,		ļ
		"5767572" "5770479" "5920114" "5998866" "6002165" "6043430"		
1	1	"6049125" "6068180" "6075283").PN.		
_	4	5998866.URPN.	USPAT	2002/06/03 07:32
1 _	9	("4766478" "5041696" "5291059"	USPAT	2002/06/03 07:32
		"5440170" "5606198" "5757066"	1	
		"5776802" "5783861" "5821628").PN.		
_	10849	(loc (lead adil chip))	USPAT;	2002/06/15 10:47
			US-PGPUB;	
			EPO; JPO;	
]			DERWENT	
-	474	((loc (lead adj1 chip))) and (inner adj	USPAT;	2002/06/15 10:52
]		lead) and (outer adj lead)	US-PGPUB;	
			EPO; JPO;	
	4222	lood noon? width	DERWENT USPAT;	2002/06/15 10:52
-	4339	lead near2 width	US-PGPUB;	2002/00/13 10.32
			EPO; JPO;	
1			DERWENT	
_	76	(((loc (lead adj1 chip))) and (inner adj	USPAT;	2002/06/15 10:52
	, ,	lead) and (outer adj lead)) and (lead near2	US-PGPUB;	l l
		width)	EPO; JPO;	
		,	DERWENT	
-	406		USPAT;	2002/06/15 10:58
	}	lead) and (outer adj lead)) and (wire	US-PGPUB;	
		wiring)	EPO; JPO;	
}			DERWENT	2002/06/15 10:58
-	280		USPAT; US-PGPUB;	2002/06/13 10:38
		lead) and (outer adj lead)) and (wire wiring)) and (width length)	EPO; JPO;	
		wiring), and (width length)	DERWENT	,
_	183	(((((loc (lead adj1 chip))) and (inner adj	USPAT;	2002/06/15 10:59
		lead) and (outer adj lead)) and (wire	US-PGPUB;	ĺ
		wiring)) and (width length)) and (bond\$3	EPO; JPO;	
	1	adj pad)	DERWENT	
-	238		USPAT;	2002/06/15 10:59
1		lead) and (outer adj lead)) and (wire	US-PGPUB;	ļ
	1	wiring)) and (width length)) and ((bond\$3	EPO; JPO;	1
	5	adj pad) electrode)	DERWENT USPAT;	2002/09/19 10:53
_	5	3933708"	US-PGPUB;	2002/03/13 10.33
	1		EPO; JPO;	
			DERWENT	
_	2	"6211573"	USPAT;	2002/09/19 10:53
			US-PGPUB;	
	1		EPO; JPO;	
			DERWENT	
-	7	"5933708" "6211573"	USPAT;	2002/09/19 10:53
			US-PGPUB;	
			EPO; JPO;	
		CO11572 TDDV	DERWENT	2002/00/10 10-54
-	0	6211573.URPN.	USPAT USPAT	2002/09/19 10:54 2002/09/19 10:54
-	6	("5072280" "5334803" "5428247" "5548160" "5612569" "5834837").PN.	OSEMI	2002/03/13 10.34
		6211573.URPN.	USPAT	2002/09/19 12:50
_	0 3	5933708.URPN.	USPAT	2002/09/19 12:50
1_	1		USPAT	2002/09/19 12:50
L	<u>_</u>	0200013 .111.		